

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	34	257/E23.123.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/28 15:05
L2	150	257/E23.127.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/28 15:23
L3	22	(US-20040178515-\$ or US-20020108768-\$ or US-20020060084-\$ or US-20020109218-\$ or US-20020195703-\$ or US-20050023572-\$ or US-20040037059-\$ or US-20040061218-\$ or US-20030183950-\$ or US-20020192876-\$ or US-20020185717-\$ or US-20030183909-\$).did. or (US-6486562-\$ or US-6324069-\$ or US-6653720-\$ or US-5583378-\$ or US-5817545-\$ or US-6400036-\$ or US-5841194-\$ or US-6992398-\$ or US-6025648-\$ or US-6518089-\$).did.	US-PGPUB; USPAT	OR	ON	2006/07/28 15:13
L4	2	"6757967".pn. "6048656".pn.	US-PGPUB; USPAT	OR	ON	2006/07/28 15:13
L5	20	257/E23.136.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/28 15:23
S41	259	(underfill or encapsulant or encapsulation or encapsulating or molding or mold) near2 (barrier or dam or wall or ridge) near10 (chip or die or integrated adj circuit) and (chip or die or integrated adj circuit) near3 (package or packaging or housing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 16:44

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S42	54	(underfill or encapsulant or encapsulation or encapsulating or molding or mold) near6 (control or controlling or regulating or regulation or regulated or controlled) near6 (barrier or dam or wall or ridge or bump or post or standoff or raised) and (chip or die or integrated adj circuit) near3 (package or packaging or housing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 16:59
S43	21	(US-20020192876-\$ or US-20050023572-\$ or US-20020060084-\$ or US-20020109218-\$ or US-20040061218-\$ or US-20020108768-\$ or US-20030183909-\$ or US-20040037059-\$ or US-20040178515-\$ or US-20030183950-\$ or US-20020185717-\$ or US-20020195703-\$).did. or (US-5817545-\$ or US-5583378-\$ or US-6025648-\$ or US-5841194-\$ or US-6324069-\$ or US-6518089-\$ or US-6486562-\$ or US-6400036-\$ or US-6653720-\$).did.	US-PGPUB; USPAT	OR	ON	2006/07/20 17:00
S44	430	(wall or stencil or barrier or ridge or raised or standoff or socket or recess\$) near4 (around or surround\$4 or circumscribing) near4 (die or chip or ic) and (encapsula\$5 or mold or molding or underfill\$4) and (chip or die or ic or integrated adj circuit) near3 (package or packaging or housing or packaged)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 17:07
S45	284	(chip or die or ic or integrated adj circuit) near4 (package or packaging or housing) and (chip or die or ic or integrated adj circuit) near5 (underfill\$4) and (chip or die or ic or integrated adj circuit or package or packaging or housing) near4 (lid or cover) near10 (encapsulant or encapsulation or resin or epoxy or adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 17:40
S46	1020	438/124.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 08:49

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S47	1001	438/126.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 08:49
S48	1559	438/127.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 08:49
S49	366	438/667.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 09:21
S50	430	438/790.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 10:17
S51	440	438/124,126,127.ccls. and (molding or encapsul\$5 or underfill\$5 or overmold\$4) near5 (barrier or dam or wall or modifier or post or ridge or separater or separating or controll\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 15:43
S52	205	438/124,126,127.ccls. and (molding or encapsul\$5 or underfill\$5 or overmold\$4) near5 (void or voided or void-free)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 13:00
S53	332	438/124,126,127.ccls. and (encapsulat\$4 or encapsulant or overmold\$4 or molding) and (underfill\$4 or under-fill\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 13:01

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S54	284	(chip or die or ic or integrated adj circuit) near4 (package or packaging or housing) and (chip or die or ic or integrated adj circuit) near5 (underfill\$4) and (chip or die or ic or integrated adj circuit or package or packaging or housing) near4 (lid or cover) near10 (encapsulant or encapsulation or resin or epoxy or adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 13:37
S55	259	(underfill or encapsulant or encapsulation or encapsulating or molding or mold) near2 (barrier or dam or wall or ridge) near10 (chip or die or integrated adj circuit) and (chip or die or integrated adj circuit) near3 (package or packaging or housing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 14:05
S56	109	(wall or stencil or barrier or ridge or raised or standoff or socket or recess\$) near4 (around or surround\$4 or circumscribing) near4 (die or chip or ic) same (encapsula\$5 or mold or molding or underfill\$4) and (chip or die or ic or integrated adj circuit) near3 (package or packaging or housing or packaged)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 14:34
S57	557	(underfill\$4 or under-fill\$4) near4 (barrier or dam or seal or blocking or blocker or sealing or dammed)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/24 14:44
S58	106	(molding or encapsul\$5 or overmold\$4) near5 (barrier or dam or wall or modifier or post or ridge or separater or separating or controll\$4) same (underfill\$4 or under-fill\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 15:48

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L8	90	((die or chip or ic or device or integrated near circuit) and (encapsulant or encapsulation or encapsulating or molding or overmolding or mold or underfill\$4 or under near fill\$4) near10 (flow\$4) near3 (control\$4 or modifier or modifying or directing or director)).clm.	US-PGPUB	OR	ON	2006/07/28 15:59
L12	8	((die or chip or ic or device or integrated near circuit) and (encapsulant or encapsulation or encapsulating or molding or overmolding or mold) near15 (underfill\$4 or under near fill\$4) near15 (dam or ridge or wall or barrier or blocker or standoff or stencil or seal)).clm.	US-PGPUB	OR	ON	2006/07/28 16:01
L13	34	((die or chip or ic or device or integrated near circuit) and (encapsulant or encapsulation or encapsulating or molding or overmolding or mold) near15 (under or underneath or below or beneath) near15 (dam or ridge or wall or barrier or blocker or standoff or stencil or seal)).clm.	US-PGPUB	OR	ON	2006/07/28 16:03
L14	8	((die or chip or ic or device or integrated near circuit) and (encapsulant or encapsulation or encapsulating or molding or overmolding or mold or molded) near10 (underfill\$4 or (under or underneath or below or beneath) near3 (encapsulation or encapsulant or encapsulating molding or mold or molded or fill)) near8 (separat\$4 or spacing or spaced)).clm.	US-PGPUB	OR	ON	2006/07/28 16:06
L15	32	((die or chip or ic or device or integrated near circuit) and (encapsulant or encapsulation or encapsulating or molding or overmolding or mold or molded) near10 (underfill\$4 or (under or underneath or below or beneath) near3 (encapsulation or encapsulant or encapsulating molding or mold or molded or fill)) near8 (flow or flowing)).clm.	US-PGPUB	OR	ON	2006/07/28 16:06